In The Claims

1-38. (Cancelled)

39. (New) An article of manufacture for polishing a substrate comprising a polishing article having a polishing surface, a plurality of perforations formed in at least a portion of the polishing article for flow of material therethrough, a plurality of grooves disposed in the polishing surface, a center portion and a perimeter portion, the center portion having a plurality of perforations, and wherein the center portion of the polishing article conducts electricity to the substrate surface.

40. (New) The article of claim 39, wherein a portion of the plurality of perforations intersect with a portion of the plurality of grooves on the polishing surface.

41. (New) The article of claim 39, wherein each of the perforations has a diameter of between about 0.016 and about 0.5 inches and are disposed between about 0.1 and about 1.0 inch from one another.

42. (New) The article of claim 39, wherein the center portion of the polishing article comprises a conductive material or a dielectric material having conductive elements disposed therein.

43. (New) The article of claim 39, wherein the plurality of grooves form a pattern comprising substantially circular concentric grooves, an X-Y pattern, or a triangular pattern on the polishing surface.

44. (New) The article of claim 43, wherein a portion of the plurality of grooves are non-intersecting and are spaced between about 0.03 and about 0.3 inches apart.

45. (New) The article of claim 39, wherein the polishing article is disposed on a perforated sub-pad.

46. (New) The article of claim 45, wherein the perforated sub-pad comprises a plurality of pores disposed therein for flow of material therethrough and the plurality of pores of the perforated sub-pad and the plurality of perforations in the polishing article are aligned for flow of material through the perforated sub-pad and the polishing article.

47. (New) An article of manufacture for polishing a substrate comprising a polishing article having a polishing surface, a plurality of perforations formed in at least a portion of the polishing article for flow of material therethrough, and a plurality of grooves disposed in the polishing surface, wherein the polishing article comprises a conductive material or a dielectric material having conductive elements disposed therein.

48. (New) The article of claim 47, wherein a portion of the plurality of perforations intersect with a portion of the plurality of grooves on the polishing surface.

49. (New) The article of claim 47, wherein each of the perforations has a diameter of between about 0.016 and about 0.5 inches and are disposed between about 0.1 and about 1.0 inch from one another.

50. (New) The article of claim 47, wherein the plurality of grooves form a pattern comprising substantially circular concentric grooves, an X-Y pattern, or a triangular pattern on the polishing surface.

51. (New) The article of claim 50, wherein a portion of the plurality of grooves are non-intersecting and are spaced between about 30 mils and about 300 mils apart.

52. (New) The article of claim 47, wherein the polishing article is disposed on a perforated sub-pad.

53. (New) The article of claim 52, wherein the perforated sub-pad comprises a plurality of pores disposed therein for flow of material therethrough and the plurality of pores of the perforated sub-pad and the plurality of perforations in the polishing article are aligned for flow of material through the perforated sub-pad and the polishing article.

54. (New) The article of claim 47, wherein the polishing article has a center portion and a perimeter portion, the center portion having a plurality of perforations.

55. (New) The article of claim 54, wherein the perimeter portion of the polishing article conducts electricity to the substrate surface.

56. (New) An article of manufacture for polishing a substrate comprising a polishing article having a polishing surface, a plurality of perforations formed in at least a portion of the polishing article for flow of material therethrough, and a plurality of grooves disposed in the polishing surface, wherein each of the perforations has a diameter of between about 0.016 and about 0.5 inches and are disposed between about 0.1 and about 1.0 inch from one another.

57. (New) An article of manufacture for polishing a substrate comprising a polishing article having a polishing surface, a plurality of perforations formed in at least a portion of the polishing article for flow of material therethrough, and a plurality of grooves disposed in the polishing surface, wherein the polishing article is disposed on a perforated sub-pad.

58. (New) The article of claim 57, wherein the perforated sub-pad comprises a plurality of pores disposed therein for flow of material therethrough and the plurality of pores of the perforated sub-pad and the plurality of perforations in the polishing article are aligned for flow of material through the perforated sub-pad and the polishing article.

59. (New) An article of manufacture for polishing a substrate comprising a polishing article having a conductive polishing surface and a plurality of perforations formed in at least a portion of the polishing article for flow of material therethrough.

60. (New) The article of claim 59, further comprising a plurality of grooves disposed in the polishing surface.

61. (New) The article of claim 59, wherein the conductive polishing surface comprises a conductive material.

62. (New) The article of claim 59, wherein the conductive polishing surface comprises a dielectric material having conductive elements embedded therein.

63. (New) An article of manufacture for polishing a substrate comprising a polishing article having a conductive polishing surface that provides a conductive path over the polishing surface and a plurality of perforations formed in at least a portion of the polishing article for flow of material therethrough.

64. (New) The article of claim 38, wherein the perimeter portion of the polishing article conducts electricity to the substrate surface.

65. (New) The article of claim 56, wherein the polishing surface has a conductive center portion that conducts electricity to the substrate surface.

66. (New) The article of claim 57, wherein the polishing surface has a conductive center portion that conducts electricity to the substrate surface.